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Nota di contenuto	<p>""ELECTRODEPOSITION ""; ""ELECTRODEPOSITION ""; ""CONTENTS ""; ""PREFACE ""; ""A REVIEW ON THE ELECTRODEPOSITION OF NICKEL: SYNTHESIS, MAGNETIC, THERMODYNAMIC PROPERTIES AND ITS POTENTIAL APPLICATIONS ""; ""ABSTRACT ""; ""INTRODUCTION ""; ""1.1. CRYSTAL STRUCTURES OF NICKEL ""; ""1.2. SYNTHESIS ""; ""1.2.1. FCC Nickel ""; ""1.2.2. HCP Nickel""; ""1.3. MAGNETIC AND THERMODYNAMIC PROPERTIES ""; ""1.4. APPLICATIONS ""; ""CONCLUSION ""; ""REFERENCES""; ""DEPOSITION AND PROPERTIES OF ELECTROCHEMICAL COMPOSITE COATINGS ""; ""ABSTRACT ""; ""INTRODUCTION ""</p> <p>""2.1. DIFFERENT TYPES OF ELECTROCHEMICAL COMPOSITE COATINGS (ECC) """"2.1.1. Nickel-Based ECC ""; ""2.1.2. Chromium-Based ECC ""; ""2.1.3. Copper-Based ECC ""; ""2.1.4. Iron-Based ECC""; ""2.1.5. Zinc-Based ECC ""; ""2.1.6. ECC Based on Noble Metals ""; ""CONCLUSION ""; ""REFERENCES ""; ""ELECTRODEPOSITION OF AU-SN ALLOYS ""; ""ABSTRACT""; ""INTRODUCTION ""; ""3.1. ELECTRODEPOSITION OF AU-SN ALLOYS FROM A SINGLE SOLUTION""; ""3.1.1. Solution Preparation ""; ""3.2. SOLUTION STABILITY ""; ""3.2.1. Solution Precipitation and Turbidity Measurements ""</p> <p>""3.2.2. Characterization of Precipitates """"3.2.3. UV/Vis Spectroscopy and X-Ray Photoelectron Spectroscopy Studies ""; ""3.3. MICROSTRUCTURE OF ELECTRODEPOSITED FILMS""; ""3.3.1. Microstructure of Eutectic Deposits and Reflowed Solder ""; ""3.4.</p>

RECOVERY OF AU FROM THE WASTE SOLUTION ""; ""3.5. SEQUENTIAL ELECTRODEPOSITION FROM TWO SEPARATE SOLUTIONS ""; ""3.5.1. Solution Preparation and Electrodeposition of Pure Au Films ""; ""3.5.2. Solution Preparation and Electrodeposition of Pure Sn Films ""; ""3.5.3. Microstructure of Sequentially Deposited Eutectic Alloys and Reflowed Solder""

""CONCLUSION """"ACKNOWLEDGMENTS ""; ""REFERENCES ""; ""ELECTROCHEMICAL CORROSION BEHAVIOUR OF LEAD a€? FREE SOLDER ALLOYS IN 3.5 % NaCl SOLUTION""; ""ABSTRACT ""; ""INTRODUCTION ""; ""4.1. ELECTROCHEMICAL CORROSION STUDY OF SN-XAG-0.5 CU SOLDER ALLOYS ""; ""4.1.1. Polarisation Study ""; ""4.1.2. Surface Characterisation Studies ""; ""4.2. ELECTROCHEMICAL CORROSION STUDY OF SN-8.5ZN-XAG-0.1AL-0.05GA SOLDER ALLOYS ""; ""4.2.1. Polarization Study ""; ""4.2.2. Surface Characterisation Studies""; ""4.3. ELECTROCHEMICAL CORROSION STUDY OF SN-8.5ZN-XAL-0.5 GA SOLDER ALLOYS ""

""4.3.1. Polarisation Study""""4.3.2. Surface Characterisation Studies: ""; ""CONCLUSION""; ""REFERENCES ""; ""PROPERTIES AND APPLICATIONS OF NICKEL COATINGS SYNTHESIZED BY PULSE ELECTRODEPOSITION""; ""ABSTRACT""; ""INTRODUCTION ""; ""5.1. THE SYNTHESIS OF NICKEL COATING WITH HIGH DENSITY NT ""; ""5.1.1. The Synthesis of Nickel Coatings with High Density NT ""; ""5.1.2. The Corrosion Property of Nickel Coating with High Density NT ""; ""5.1.3. The Semiconducting Behavior of Passive Film of NT Nickel ""; ""5.2. INHIBITION OF HYDROGEN BLISTER ON CUa€?SN ALLOY COATINGS ""

""5.2.1. Influence of Current Density on Hydrogen Permeation ""

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